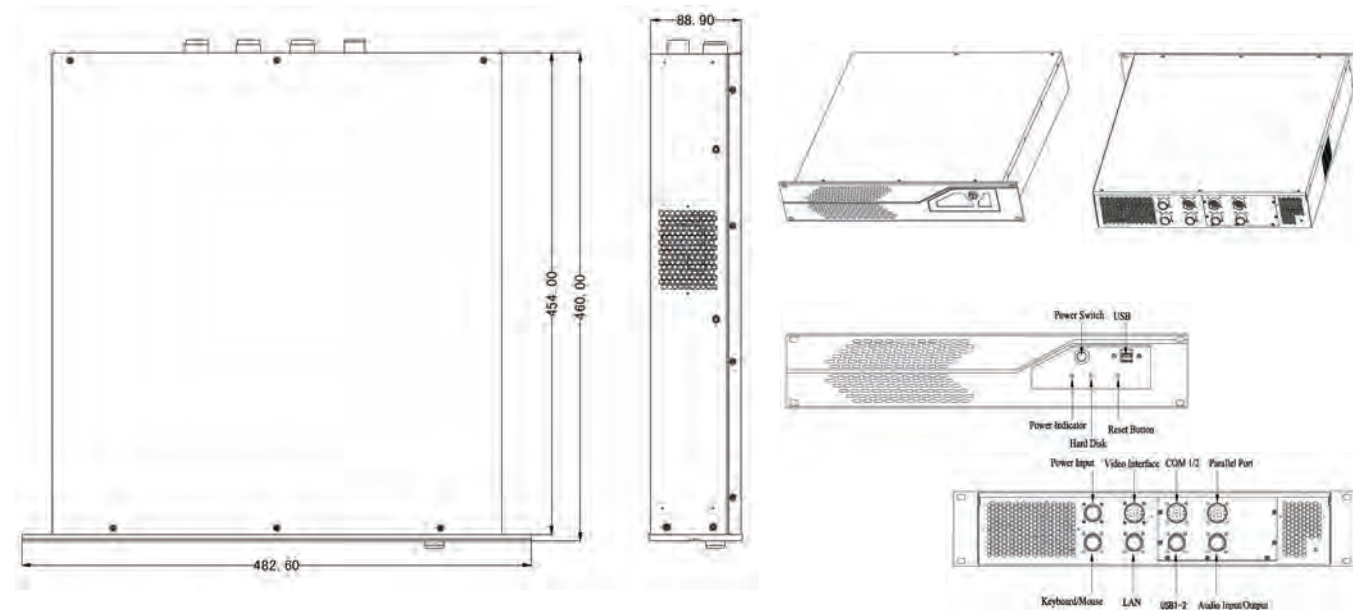


JPC-8202

Rugged 2U 19" Rackmount Computer with Intel® Core 2 Duo Platform



Dimensions



Features

- Adopts ATX mainboard, supports Core 2 Duo processor and FSB 800MHz
- Supports 4 x PCI, 2 x PCI-Ex1, 1 x PCI-E x 16
- Provides all kinds of I/O interface, optional aviation connector as per requirement
- Supports industrial class and military class EMC/EMI performance
- Supports full range of rugged performance
- Supports free customization

OPTIONAL SPECIFICATIONS

EMC/EMI

Normal-Class	RE: EN55022 Radiated Disturbance, 10m Distance, A/B* Class CE: EN55022 Conducted Disturbance, Power Leads, Electric Field, A/B* Class CS: IEC61000-4-6 Conducted Disturbance Immunity, 1/2/3* Class RS: IEC61000-4-3 Radiated, Electromagnetic Field Immunity, 1/2/3*4 Class ESD: IEC61000-4-2 Electrostatic Discharge Immunity, 1/2/3*4 -Class EFT: IEC61000-4-4 Electrical Fast Transient/Burst Immunity 1/2/3*4 Class SURGE: IEC61000-4-5 Surge Immunity, 1/2/3/4 Class, 1/2/3*4 Class
High-Class	RE102: MIL-STD-461E Radiated Emissions, Electric Field, 10KHz-18GHz CE102: MIL-STD-461E Conducted Emissions, Power Leads, 10KHz-10MHz CS101: MIL-STD-461E Conducted Susceptibility, Power Leads, 30Hz-150KHz CS114: MIL-STD-461E Conducted Susceptibility, Bulk Cable Injection, 10KHz-200Mhz RS103: MIL-STD-461E Radiated Susceptibility, Electric Field, 2MHz-40GHz
Others	Special customization

Environment

High-Temperature (Working)	Working: 50°C, MIL-STD-810F Method 501.4 Procedure II - Operation Working: 55°C, MIL-STD-810F Method 501.4 Procedure II - Operation* Working: 60°C, MIL-STD-810F Method 501.4 Procedure II - Operation Special customization
High-Temperature (Storage)	Storage: 55°C, MIL-STD-810F Method 501.4 Procedure I - Storage Storage: 60°C, MIL-STD-810F Method 501.4 Procedure I - Storage * Storage: 65°C, MIL-STD-810F Method 501.4 Procedure I - Storage Special customization
Low-Temperature (Working)	Working: -15°C, MIL-STD-810F Method 502.4 Procedure II - Operation Working: -20°C, MIL-STD-810F Method 502.4 Procedure II - Operation* Working: -25°C, MIL-STD-810F Method 502.4 Procedure II - Operation Special Customization
Low-Temperature (Storage)	Storage: -20°C, MIL-STD-810F Method 502.4 Procedure I - Storage Storage: -30°C, MIL-STD-810F Method 502.4 Procedure I - Storage* Storage: -40°C, MIL-STD-810F Method 502.4 Procedure I - Storage Special customization
Relative Humidity	35°C, 75% @24H, MIL-STD-810F Method 507.4 40°C, 80% @24H, MIL-STD-810F Method 507.4 40°C, 95% @24H, MIL-STD-810F Method 507.4* Special customization
Anti-Shocking	20g/11ms, MIL-STD-810F Method 516.5 Special customization
Anti-Vibration	5-30Hz/0.5mm, 30-500Hz/1.5g, 50-500Hz/3.0g, MIL-STD-810F Method 514.5 Special Customization

Drop	80cm height drops from 6 faces, 3 edges and 1 corner, MIL-STD-810F Method 516.5 Special customization
IP Protection	N/A Special customization
Conformal Coating	Anti-Fungus, MIL-STD-810F Method 508.4 Anti-Salt Fog, MIL-STD-810F Method 509.4
Rear I/O Panel	Special customization : I/O interface with aviation connector as per requirement Length of aviation cables as per requirement

Electrical Safety

Grounding Resistance	≤90mΩ, 25A@ 60s, IEC60950
Earth Leakage Current	≤3.5mA, @60s, IEC60950
Electric Strength	10mA/1500V@ 60s, IEC60950
Insulation Resistance	≥100MΩ, 500VDC@ 30s, IEC60950
Others	Special Customization

Note 1 : * is recommended

How to choose ODM service and place order

Step 1: Check all the basic specification whether it could be a satisfactory solution.
Step 2: Choose required ODM items from optional specification and ignore those unwanted
For example: JPC-8202
T7500/4GB RAM/1x80G HDD
Normal-Class EMC/EMI
Working Temperature: -15°C~+55°C
2 x USB with aviation connector and 1m long cable
1 x COM with aviation connector and 1m long cable



BASIC SPECIFICATIONS

System	
Processor	Intel® Core 2 Duo or Intel® Dual-core processor with 800/533 MHz FSB Intel® Core 2 Duo T8300/2.4GHz/800FSB/3MB-L2/45nm Intel® Core 2 Duo T7500/2.2GHz/800FSB/4MB-L2/65nm* Intel® Core 2 Duo T7300/2.0GHz/800FSB/4MB-L2/65nm
Chipset	Intel® GME965 + ICH8M-E
Memory	Supports onboard 2GB DDR2 667 RAM and 1x200-pin SODIMM, up to 4GB
Hardware Monitor	Monitors system status, voltage, temperature and fan speed
Watchdog Timer	1~255 sec./min. timer system reset or interrupt, setup by software
Form Factor	ATX Architecture
Expansion Interface	1 x PCI-Ex16, supports PCI-E Rev 1.1 and relevant add-on card 2 x PCI-Ex1, supports PCI-E Rev 1.1 and relevant add-on card 4 x PCI, supports PCI Rev 2.3 and relevant add-on card
Storage	
SATA Interface	Available max. 3 x SATAII interfaces, supports RAID 0,1,2 and speed 300MB/s
IDE Interface	Available max. 1 x IDE interface
Drive Bay	Available max. 2 x 2.5" bay Special customization
HDD Capacity	Available wide-temperature 80G Available normal-temperature 160G/250G/320G or other
Display	
Graphic Processor	Mobile Intel® Graphic Media Accelerator X3100 with 500MHz
Video Memory	384MB share with system memory
Resolution	VGA mode supports 1024 x 768, 1440 x 900, 1680 x 1050, 1920 x 1200, 1280 x 1024
Others	Supports VGA hot plug
Ethernet	
Chipset	Available max. onboard 2 x Intel® 82573E network chipset
Speed	Max. 1000Mbps
Performance	TCP segmentation offload, TCP, UDP, IPv4 checksum offload, interrupt moderation, jumbo frames

I/O Interface	
VGA	Available max. 1 x VGA
RJ-45	Available max. 2 x RJ-45
USB	Front panel: available max. 2 x USB2.0 Ports Rear panel: available max. 4 x USB2.0 Ports
Serial Port	Available max. 2 x RS-232 of 9-lines in rear I/O panel
Parallel Port	Available max. 1 x LPT, supports EPP/ECP
GPIO	Available max. 8 x Digital input or output
Audio	AC'97, available max. 1 x Speaker-out, 1 x Line-in and 1 x Mic-in

Power Supply	
Power Input	Available 9v~36v DC Power input Available AC100-240V/47-63Hz input
Power Type	Available DC-to-ATX Available AC-to-ATX
Power Consumption	TDP with Intel® Core 2 Duo T7500/4GB DDR2 667 +5V@ 4.49A; +3.3V@ 1.44A; +12V@ 4.72A

Other Characteristics	
Dimensions(WxDxH)	482.60mm x 460.00mm x 89.00mm (Default)
Color	Available military green
Reliability	MTBF ≥ 10000 h MTTR ≤ 0.5 h
Operating System	Supports Windows 2000 / XP/ Vista / win7 Supports Windows XP Embedded Supports Windows CE and Vxworks Supports Linux Rev 2.6 or later